

Electronic Patent Application Fee Transmittal

Application Number:	10666399
Filing Date:	18-Sep-2003
Title of Invention:	Molded chip fabrication method and apparatus
First Named Inventor/Applicant Name:	Michael S. Leung
Filer:	Jaye G. Heybl/Marianne Middleton
Attorney Docket Number:	P0298US-7

Filed as Large Entity

Utility under 35 USC 111(a) Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Claims in excess of 20	1202	1	52	52
Independent claims in excess of 3	1201	1	220	220

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Extension - 3 months with \$0 paid	1253	1	1110	1110
Miscellaneous:				
Total in USD (\$)				1382